

QUALITEK® 360
NO CLEAN
ZERO HALOGEN FLUX

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Description

Qualitek® 360 No Clean Flux is a homogeneous mixture of zero halogen, low solids flux system, designed specifically for use with conventional Sn/Pb alloys **and** high temperature lead free systems. 360 exhibits excellent wetting and fluxing characteristics with essentially no post-soldering residue. The unique solvent system in 360 allows for a very broad process window and has been successful in drop jet fluxing applications.

Main Features

- Zero Halogen
- Excellent wetting on virtually all types of substrates
- Results in bright, shiny solder joints
- Rosin/Resin free
- Compatible with Lead-free & Leaded Solder Systems

Technical Data

	Specification	Test Method
Flux Classification	ORL0	IPC-J-STD-004B
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Corrosion	Pass	IPC-TM-650 2.6.15
Flash Point	58 °F	
SIR	Pattern up 2.06x 10 ¹¹ ohms	IPC-TM-650 2.6.3.3
	Pattern down 1.93 x 10 ¹¹ ohms	
Acid Value	14.0 – 18.0	IPC-TM-650 2.3.13
Specific Gravity	0.813 ± 0.005	
Solids Content	2.3 – 2.7	IPC-TM-650 2.3.34

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Applications

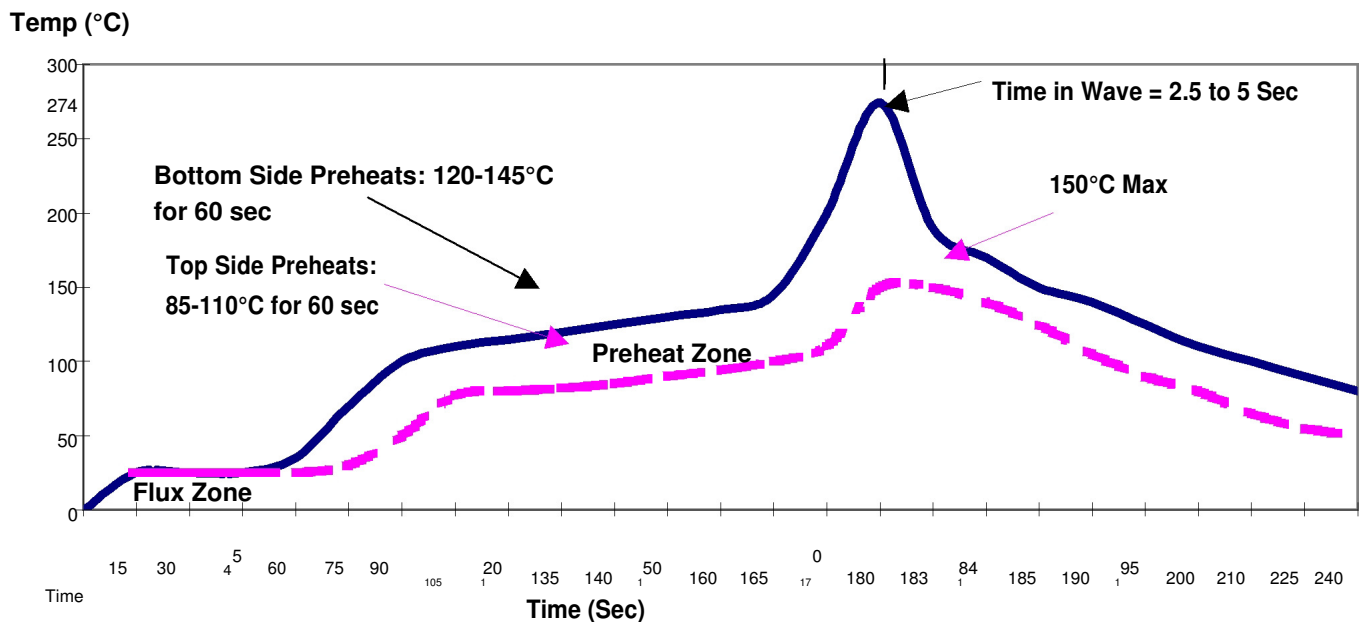
Flux Application

For mass wave soldering of OSP and plated circuit boards, spray, foam or wave fluxing can be utilized to apply this flux. Flux deposition density and uniformity are critical to successful use of low solids no-clean flux. If foam fluxing, the foam fluxer should be supplied with compressed air, which is free of oil and water. The flux tank should be full at all times. The surface of the flux should be 1-1/2 inches above the top of the flux aerator, or flux stone. Pressure should then be adjusted to produce the optimum foam height with a fine uniform foam head. After fluxing, an air knife should be used to remove excessive flux from the assembly.

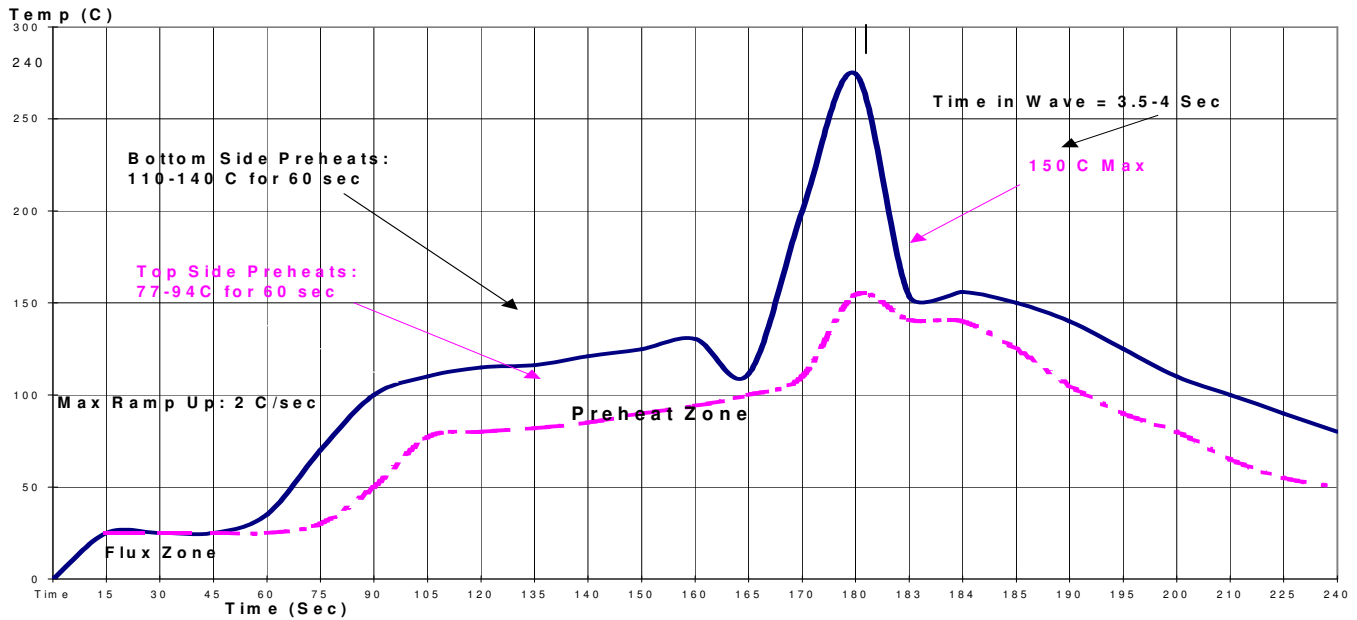
Uniformity of the spray flux coating can be visually checked by running a tempered glass plate (usually supplied by machine manufacturer) through the spray and preheat sections, and inspected before going across the wave.

OPERATING PARAMETERS		TYPICAL LEVEL
Amount of flux		Foam, Wave: 1000-2000 µg/in ² solids Spray: 750-1500 µg/in ² solids
Foam Fluxing Parameters		
	Foam Stone Pore Size	20-50 µm
	Flux Level Above Stone	1-1 1/2 inches (25-40mm)
	Chimney Opening	3/8-1/2 inch (10-13 mm)
	Air Pressure	1-2 psi
Top Side Preheat Temperature		190-230 °F (85-110 °C)
Bottom Side Preheat Temperature		65 °F (35 °C) higher than topside
Conveyor Speed		4-6 feet/minute(1.2-1.8 meters/minute)
Contact Time in the Solder (including Chip & Lambda)		2.5-4.5 seconds
Solder Pot Temperature		
	Sn96.5/Ag3.5	500-530 °F (260-276 °C)
	Sn95/Ag5	536-565 °F (280-296 °C)
	Sn99.3/Cu0.7	510-530 °F (265-276 °C)
	SnAgCu	520-530 °F (271-276 °C)
	Sn95/Sb5	536-565 °F (280-296 °C)

TYPICAL Lead Free Wave Solder Profile (SNAGCU)



TYPICAL Leaded Wave Solder Profile (Sn63/Pb37)



Process Control

Control of flux during use is necessary to assure consistent flux deposition on the circuit board. Due to the very low solids content of no clean fluxes, specific gravity is not an accurate measure for assessing solids content. Monitoring and controlling acid number by titration is recommended for maintaining the proper flux concentration. Control of the flux can be achieved with 300B thinner to maintain fluxing activity.

Over time debris and contaminants may accumulate in the flux reservoir. Therefore, periodically replacing the flux and cleaning the reservoir is recommended for consistent performance and minimizing debris build-up.

Cleaning

360F is a no clean formulation therefore the residues do not need to be removed for typical applications. If residue removal is desired, the use of Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) will aid in residue removal.

Storage & Shelf Life

Liquid flux should be stored in a 65-80°F environment away from direct heat and flame. Shelf life is 2 years from date of manufacture.

Packaging

360 No Clean Zero Halogen Flux is available in

- 1 Gallon/1 Liter containers
- 5 Gallon/5 Liter containers
- 55 Gallon/20 Liter containers

Disposal

360 contains hazardous ingredients therefore the flux should be disposed of in accordance with federal, state, local & federal authority requirements.

Qualitek[®] is a brand of Qualitek International, Inc.